

Hex D Flip-Flop with Reset

Features

- Buffered Inputs
- Typical Propagation Delay
 - 6.4ns at $V_{CC} = 5V$, $T_A = 25^\circ C$, $C_L = 50pF$
- Exceeds 2kV ESD Protection MIL-STD-883, Method 3015
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption
- Balanced Propagation Delays
- AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
- $\pm 24mA$ Output Drive Current
 - Fanout to 15 FAST™ ICs
 - Drives 50 Ω Transmission Lines

Description

The CD74AC174 and 'ACT174 are hex D flip-flops with reset that utilize Advanced CMOS Logic technology. Information at the D input is transferred to the Q output on the positive-going edge of the clock pulse. All six flip-flops are controlled by a common clock (CP) and a common reset (\overline{MR}). Resetting is accomplished by a low voltage level independent of the clock.

Ordering Information

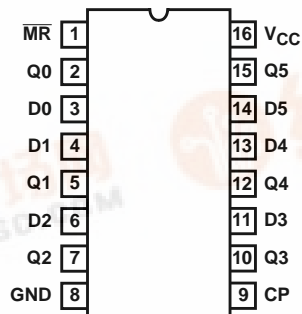
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD74AC174E	-55 to 125	16 Ld PDIP
CD74AC174M	-55 to 125	16 Ld SOIC
CD54ACT174F3A	-55 to 125	16 Ld CERDIP
CD74ACT174E	-55 to 125	16 Ld PDIP
CD74ACT174M	-55 to 125	16 Ld SOIC

NOTES:

1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
2. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local TI sales office or customer service for ordering information.

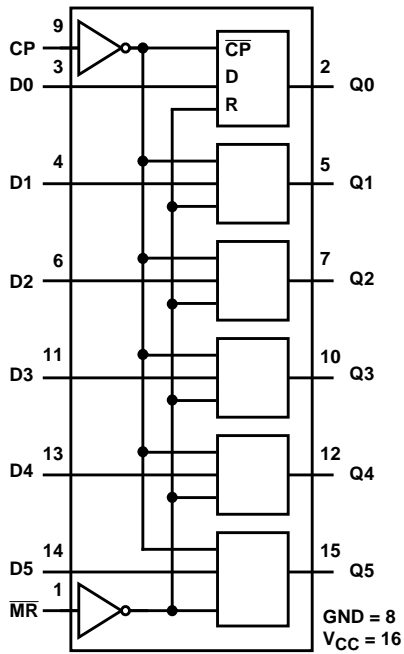
Pinout

CD54ACT174
(CERDIP)
CD74AC174, CD74ACT174
(PDIP, SOIC)
TOP VIEW



CD74AC174, CD54/74ACT174

Functional Diagram



TRUTH TABLE (EACH FLIP-FLOP)

INPUTS			OUTPUTS
RESET (MR)	CLOCK CP	DATA D _n	Q _n
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	Q ₀

H = High Level (Steady State)

L = Low Level (Steady State)

X = Irrelevant

↑ = Transition from Low to High level

Q₀ = Level before the Indicated Steady-State Input conditions were established.

CD74AC174, CD54/74ACT174

Absolute Maximum Ratings

DC Supply Voltage, V_{CC}	-0.5V to 6V
DC Input Diode Current, I_{IK}	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, I_{OK}	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 50mA$
DC Output Source or Sink Current per Output Pin, I_O	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 50mA$
DC V_{CC} or Ground Current, I_{CC} or I_{GND} (Note 3)	$\pm 100mA$

Thermal Information

Thermal Resistance (Typical, Note 5)	θ_{JA} ($^{\circ}C/W$)
PDIP Package	90
SOIC Package	160
Maximum Junction Temperature (Plastic Package)	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$ (SOIC - Lead Tips Only)

Operating Conditions

Temperature Range, T_A	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, V_{CC} (Note 4)	
AC Types	1.5V to 5.5V
ACT Types	4.5V to 5.5V
DC Input or Output Voltage, V_I , V_O	0V to V_{CC}
Input Rise and Fall Slew Rate, dt/dv	
AC Types, 1.5V to 3V	50ns (Max)
AC Types, 3.6V to 5.5V	20ns (Max)
ACT Types, 4.5V to 5.5V	10ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

3. For up to 4 outputs per device, add $\pm 25mA$ for each additional output.
4. Unless otherwise specified, all voltages are referenced to ground.
5. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V_{CC} (V)	25 $^{\circ}C$		-40 $^{\circ}C$ TO 85 $^{\circ}C$		-55 $^{\circ}C$ TO 125 $^{\circ}C$		UNITS	
		V_I (V)	I_O (mA)		MIN	MAX	MIN	MAX	MIN	MAX		
AC TYPES												
High Level Input Voltage	V_{IH}	-	-	1.5	1.2	-	1.2	-	1.2	-	V	
				3	2.1	-	2.1	-	2.1	-	V	
				5.5	3.85	-	3.85	-	3.85	-	V	
Low Level Input Voltage	V_{IL}	-	-	1.5	-	0.3	-	0.3	-	0.3	V	
				3	-	0.9	-	0.9	-	0.9	V	
				5.5	-	1.65	-	1.65	-	1.65	V	
High Level Output Voltage	V_{OH}	V_{IH} or V_{IL}	-0.05	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	-4	3	2.58	-	2.48	-	2.4	-	V
			-24	-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
-50 (Note 6, 7)	-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V			

CD74AC174, CD54/74ACT174

DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V _{CC} (V)	25°C		-40°C TO 85°C		-55°C TO 125°C		UNITS
		V _I (V)	I _O (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
Low Level Output Voltage	V _{OL}	V _{IH} or V _{IL}	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I _I	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μA
Quiescent Supply Current MSI	I _{CC}	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μA
ACT TYPES											
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V _{OH}	V _{IH} or V _{IL}	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V _{OL}	V _{IH} or V _{IL}	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I _I	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μA
Quiescent Supply Current MSI	I _{CC}	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μA
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI _{CC}	V _{CC} -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

NOTES:

6. Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
7. Test verifies a minimum 50Ω transmission-line-drive capability at 85°C, 75Ω at 125°C.

ACT Input Load Table

INPUT	UNIT LOAD
Dn, \overline{MR}	0.5
CP	0.83

NOTE: Unit load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

CD74AC174, CD54/74ACT174

Prerequisite For Switching Function

PARAMETER	SYMBOL	V _{CC} (V)	-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	MAX	MIN	MAX	
AC TYPES							
Data to CP Set-Up Time	t _{SU}	1.5	2	-	2	-	ns
		3.3 (Note 9)	2	-	2	-	ns
		5 (Note 10)	2	-	2	-	ns
Hold Time	t _H	1.5	33	-	38	-	ns
		3.3	3.7	-	4.2	-	ns
		5	2.6	-	3	-	ns
Removal Time, \overline{MR} to CP	t _{REM}	1.5	1.5	-	1.5	-	ns
		3.3	1.5	-	1.5	-	ns
		5	1.5	-	1.5	-	ns
\overline{MR} Pulse Width	t _W	1.5	44	-	50	-	ns
		3.3	4.9	-	5.6	-	ns
		5	3.5	-	4	-	ns
CP Pulse Width	t _W	1.5	57	-	65	-	ns
		3.3	6.4	-	7.3	-	ns
		5	4.6	-	5.2	-	ns
CP Frequency	f _{MAX}	1.5	9	-	8	-	MHz
		3.3	77	-	68	-	MHz
		5	108	-	95	-	MHz
ACT TYPES							
Data to CP Set-Up Time	t _{SU}	5 (Note 10)	2	-	2	-	ns
Hold Time	t _H	5	2.2	-	2.5	-	ns
Removal Time, \overline{MR} to CP	t _{REM}	5	1.5	-	1.5	-	ns
\overline{MR} Pulse Width	t _W	5	3.5	-	4	-	ns
Clock Pulse Width	t _W	5	5.4	-	6.2	-	ns
CP Frequency	f _{MAX}	5	91	-	80	-	MHz

Switching Specifications Input t_r, t_f = 3ns, C_L = 50pF (Worst Case)

PARAMETER	SYMBOL	V _{CC} (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
AC TYPES									
Propagation Delay, CP to Qn	t _{PLH} , t _{PHL}	1.5	-	-	154	-	-	169	ns
		3.3 (Note 9)	4.9	-	17.2	4.7	-	18.9	ns
		5 (Note 10)	3.5	-	12.3	3.4	-	13.5	ns

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Switching Specifications Input t_r , $t_f = 3\text{ns}$, $C_L = 50\text{pF}$ (Worst Case) (Continued)

PARAMETER	SYMBOL	V_{CC} (V)	-40°C TO 85°C			-55°C TO 125°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	
Propagation Delay, \overline{MR} to Qn	t_{PLH} , t_{PHL}	1.5	-	-	165	-	-	181	ns
		3.3	5.2	-	18.5	5.1	-	20.3	ns
		5	3.7	-	13.2	3.6	-	14.5	ns
Input Capacitance	C_I	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C_{PD} (Note 11)	-	-	37	-	-	37	-	pF
ACT TYPES									
Propagation Delay, CP to Qn	t_{PLH} , t_{PHL}	5 (Note 10)	3.6	-	12.6	3.5	-	14	ns
Propagation Delay, \overline{MR} to Qn	t_{PLH} , t_{PHL}	5	4	-	14.1	3.9	-	15.5	ns
Input Capacitance	C_I	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C_{PD} (Note 11)	-	-	37	-	-	37	-	pF

NOTES:

8. Limits tested 100%.
9. 3.3V Min is at 3.6V, Max is at 3V.
10. 5V Min is at 5.5V, Max is at 4.5V.
11. C_{PD} is used to determine the dynamic power consumption per flip-flop.
 $P_D = C_{PD} V_{CC}^2 f_i + \Sigma (C_L + V_{CC}^2 f_o) + V_{CC} \Delta I_{CC}$ where f_i = input frequency, f_o = output frequency, C_L = output load capacitance, V_{CC} = supply voltage.

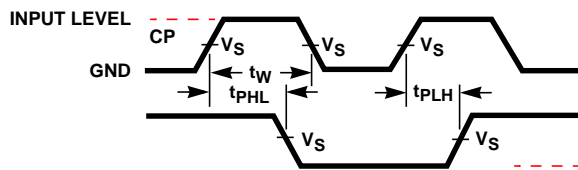


FIGURE 1. PROPAGATION DELAYS

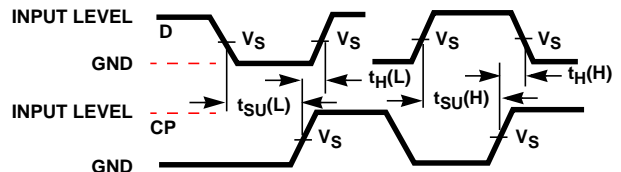


FIGURE 3.

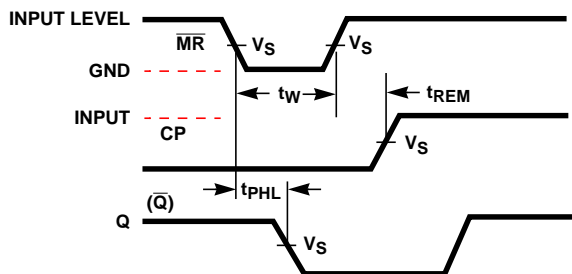
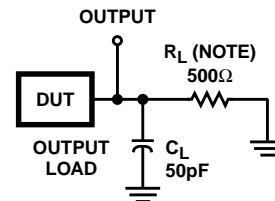


FIGURE 2. \overline{MR} OR \overline{SET} PREREQUISITE AND PROPAGATION DELAYS



NOTE: For AC Series Only: When $V_{CC} = 1.5\text{V}$, $R_L = 1\text{k}\Omega$.

	AC	ACT
Input Level	V_{CC}	3V
Input Switching Voltage, V_S	$0.5 V_{CC}$	1.5V
Output Switching Voltage, V_S	$0.5 V_{CC}$	$0.5 V_{CC}$

FIGURE 4. PROPAGATION DELAY TIMES

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